**Technical datasheet**

**Polymer Removal in Electronic Applications**

**Depotting, Decapsulating and Conformal Coating Removal**

**TIPS TO ENSURE MAXIMUM PRODUCT EFFECTIVENESS:**
Before using any polymer removal product, refer to the product SDS for handling and safety information.
- Follow the temperature guidelines provided
- Agitation will improve product effectiveness (ultrasonic or mechanical)
- Keep container loosely covered to prevent solvent loss

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<th>Polymer Being Removed</th>
<th>Dynasolve™ Product</th>
<th>Specific Product Usage Guidelines</th>
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| Epoxy-amine cured      | Dynasolve™ 185     | 1. Heat Dynasolve 185 to 200°F (93°C) and immerse part.  
                          |                    | 2. Observe carefully. If epoxy appears unaffected after 1 hour, increase temperature to 250° – 300°F (121° – 148°C).  
                          |                    | 3. After successful removal of epoxy, rinse with alcohol or water.  
                          |                    | 4. If epoxy appears unaffected after 2 hours, call technical support. |
| Epoxy-anhydride cured  | Dynasolve™ 700 Series | 1. Heat Dynasolve 700 Series solvent to 245°F (118°C) and immerse part.  
                          |                    | 2. Observe carefully. If epoxy appears unaffected after 1 hour, increase temperature to 250° – 300°F (121° – 148°C).  
                          |                    | 3. After successful removal of epoxy, rinse with alcohol or water.  
                          |                    | 4. If epoxy appears unaffected after 2 hours, call technical support. |
| Cured urethane (depotting and decapsulating) | Dynasolve™ 700 Series | 1. Heat Dynasolve 700 Series solvent to 200°F (93°C) and immerse part.  
                          |                    | 2. Observe carefully. If urethane appears unaffected after 1 hour, increase temperature to 250° – 300°F (121° – 148°C).  
                          |                    | 3. After successful removal of urethane, rinse with alcohol or water.  
                          |                    | 4. If urethane appears unaffected after 2 hours, call technical support. |
| Urethane (conformal coating and removal) | Uresolve 411 | 1. Immerse board in Uresolve 411 at room temperature.  
                          |                    | 2. Observe carefully. Once conformal coating has been removed, it is critical to rinse with alcohol prior to rinsing with water.  
                          |                    | 3. If milky residue remains, dissolving action is not complete and the device should be immersed again.  
                          |                    | 4. For partial/spot removal, apply locally with appropriate tools.  
                          |                    | • Uresolve 411 is also available in a thick, gelatinous form for spot removal.  
<pre><code>                      |                    | • Uresolve Blue is a less aggressive, vinyl safe version of Uresolve 411. |
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| Cured silicone       | Dynasolve™ 200 Series | 1. Ensure the part is completely free of water.  
2. Immerse part in Dynasolve 200 Series solvent.  
   - Dynasolve 220, 225, and 230 should be used at room temperature.  
   - Dynasolve 218 should be used at 125°F (52°C).  
3. Once cured silicone has been removed, it is critical to rinse with alcohol prior to rinsing the water.  
4. Observe carefully. If silicone is unaffected by the Dynasolve 200 Series solvent after 4 hours, call technical support. |
| Cured acrylics       | Dynasolve™ 699   | 1. Immerse part in Dynasolve 699 at room temperature.  
2. If acrylic appears unaffected after 1 hour, increase temperature to 150° – 200°F (65° – 93°C).  
3. Once cured acrylic material has been removed, rinse with alcohol or water.  
4. If acrylic is unaffected by Dynasolve 699 after 2 hours, call technical support. |
| Cured polyimides     | Dynasolve™ CU-7  | 1. Immerse part in Dynasolve CU-7 at 180°F (82°C) and immerse part.  
2. Observe carefully. If polyimide material appears unaffected after 1 hour, increase temperature to 250° – 350°F (121° – 176°C).  
3. After successful removal of polyimide material, rinse with alcohol or water.  
4. If polyimide material is unaffected by Dynasolve CU-7 after 2 hours, call technical support. |

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